

Product Summary

BV _{DSS}	R _{D(on)} max	I _D max T _C = +25°C
100V	28mΩ @ V _{GS} = 10V	55A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Engine management systems
- Body control electronics
- DC-DC converters

Features and Benefits

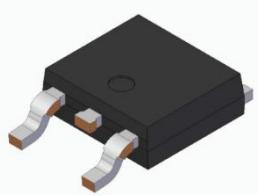
- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching – Ensures More Reliable and Robust End Application
- Low R_{D(on)} – Minimizes Power Losses
- Low Q_G – Minimizes Switching Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMNH10H028SK3Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

<https://www.diodes.com/quality/product-definitions/>

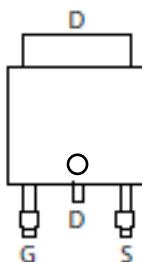
Mechanical Data

- Package: TO252
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.33 grams (Approximate)

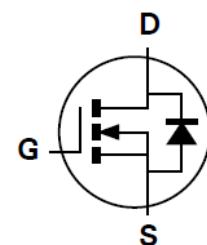
TO252 (DPAK)



Top View



Pinout Top View



Equivalent Circuit

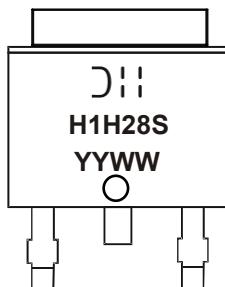
Ordering Information (Note 4)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
DMNH10H028SK3Q-13	TO252 (DPAK)	2,500	Tape & Reel

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



DII = Manufacturer's Marking
H1H28S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 25 = 2025)
WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	± 20	V
Continuous Drain Current, $V_{GS} = 10\text{V}$	$T_C = +25^\circ\text{C}$ $T_C = +100^\circ\text{C}$	I_D	55 39	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)		I_{DM}	58	A
Maximum Continuous Body Diode Forward Current (Note 5)		I_S	2.2	A
Avalanche Current, $L = 0.1\text{mH}$		I_{AS}	29	A
Avalanche Energy, $L = 0.1\text{mH}$		E_{AS}	43	mJ

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	2.0	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	74	$^\circ\text{C/W}$
	$t < 10\text{s}$		25	
Total Power Dissipation (Note 6)		P_D	3.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	40	$^\circ\text{C/W}$
	$t < 10\text{s}$		13	
Thermal Resistance, Junction to Case		$R_{\theta JC}$	1.2	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +175	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	$V_{GS} = 0, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current, $T_J = +25^\circ\text{C}$	I_{DSS}	—	—	1	μA	$V_{DS} = 100\text{V}, V_{GS} = 0$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	2.0	2.5	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	20	28	$\text{m}\Omega$	$V_{GS} = 10\text{V}, I_D = 20\text{A}$
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	$V_{GS} = 0, I_S = 1.0\text{A}$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	2,245	—	pF	$V_{DS} = 50\text{V}, V_{GS} = 0, f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	173	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	68	—	pF	
Gate Resistance	R_g	—	1.9	—	Ω	
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	36	—	nC	$V_{DS} = 50\text{V}, I_D = 20\text{A}$
Total Gate Charge ($V_{GS} = 6\text{V}$)	Q_g	—	22	—	nC	
Gate-Source Charge	Q_{gs}	—	7.3	—	nC	
Gate-Drain Charge	Q_{gd}	—	9.2	—	nC	
Turn-On Delay Time	$t_{D(\text{ON})}$	—	6.4	—	ns	$V_{GS} = 10\text{V}, V_{DS} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$
Turn-On Rise Time	t_R	—	5.8	—	ns	
Turn-Off Delay Time	$t_{D(\text{OFF})}$	—	17.8	—	ns	
Turn-Off Fall Time	t_f	—	4.8	—	ns	
Body Diode Reverse-Recovery Time	t_{RR}	—	35	—	ns	$I_f = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Body Diode Reverse-Recovery Charge	Q_{RR}	—	47	—	nC	$I_f = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

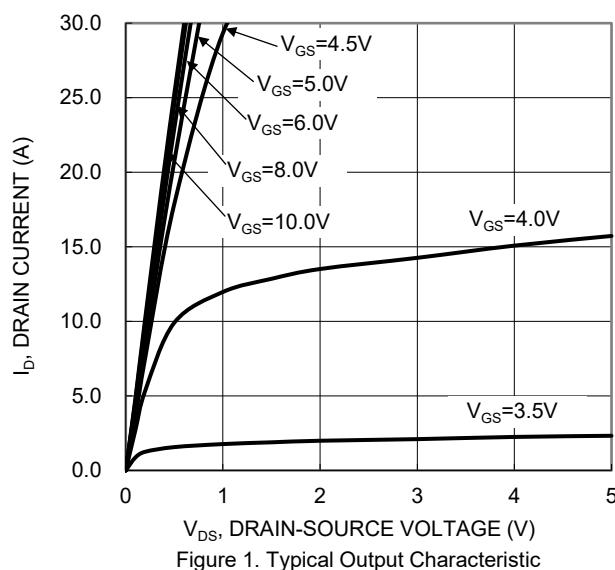


Figure 1. Typical Output Characteristic

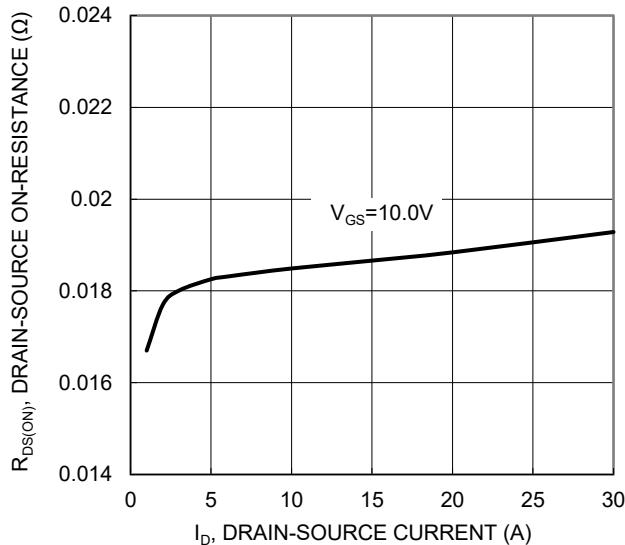


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

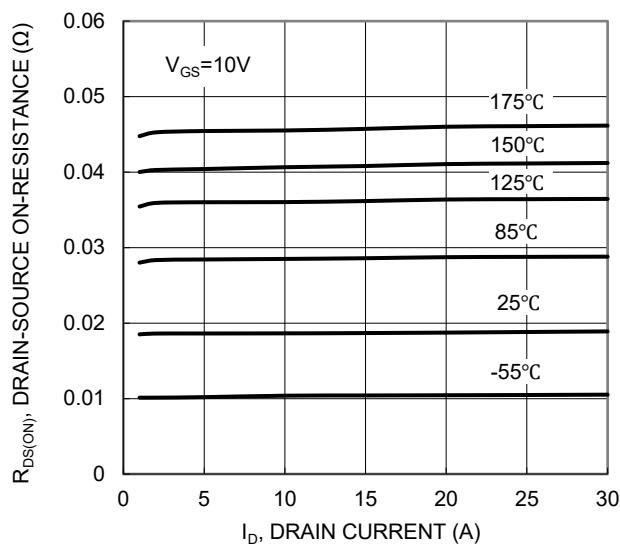


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

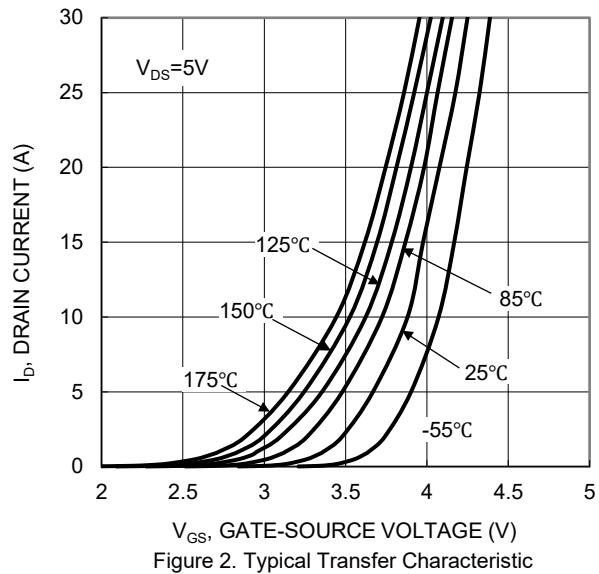


Figure 2. Typical Transfer Characteristic

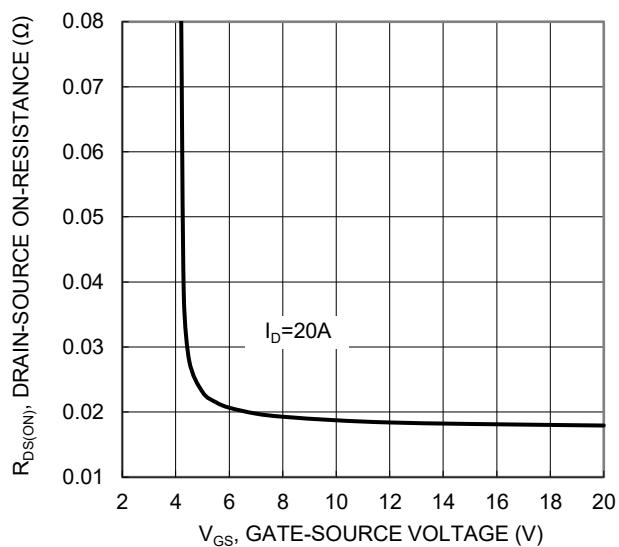


Figure 4. Typical Transfer Characteristic

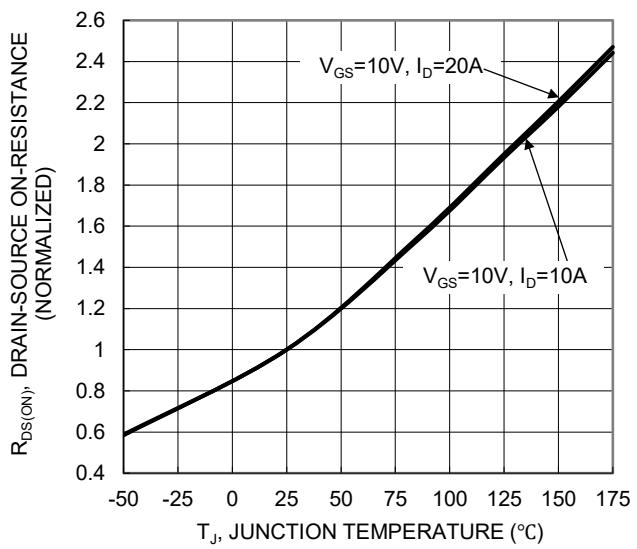


Figure 6. On-Resistance Variation with Temperature

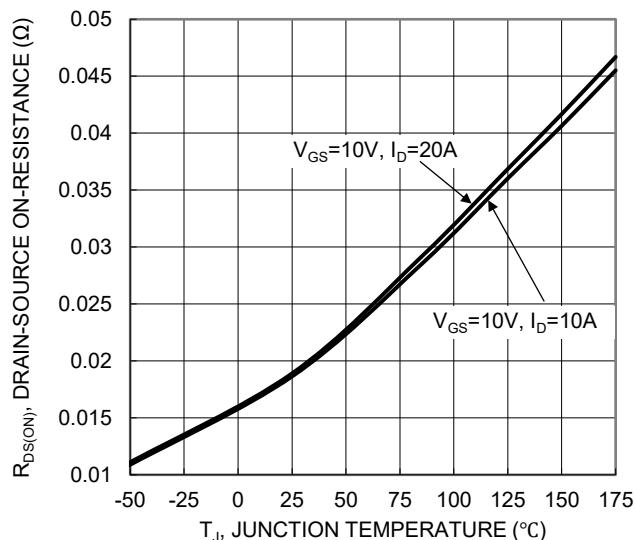


Figure 7. On-Resistance Variation with Temperature

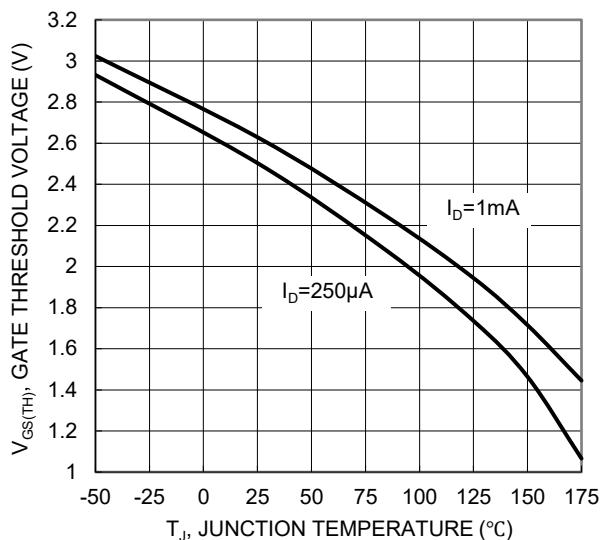


Figure 8. Gate Threshold Variation vs. Junction Temperature

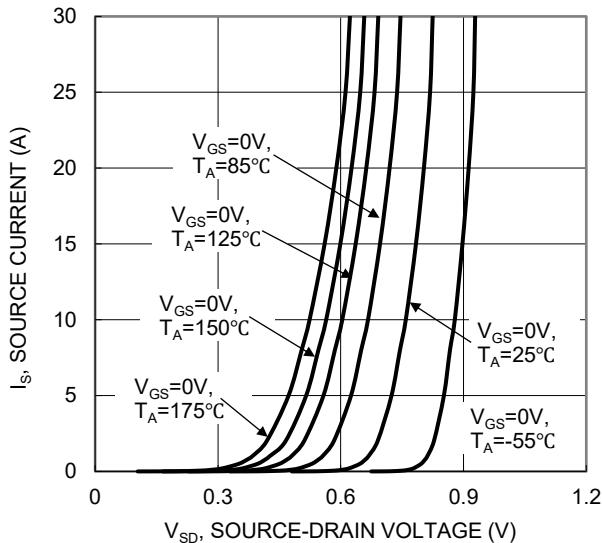


Figure 9. Diode Forward Voltage vs. Current

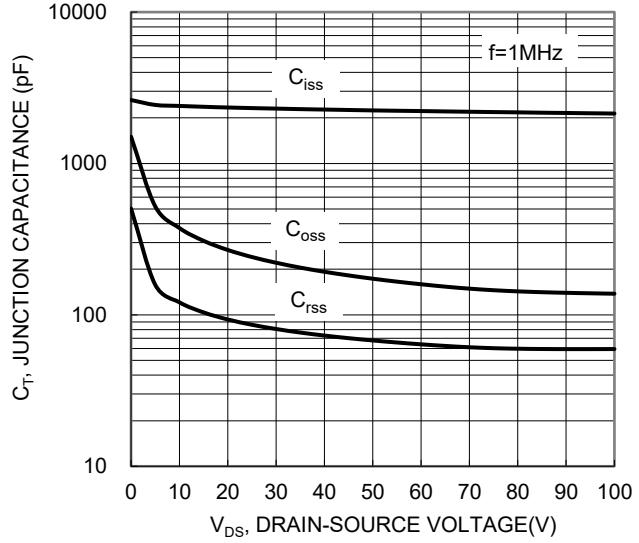


Figure 10. Typical Junction Capacitance

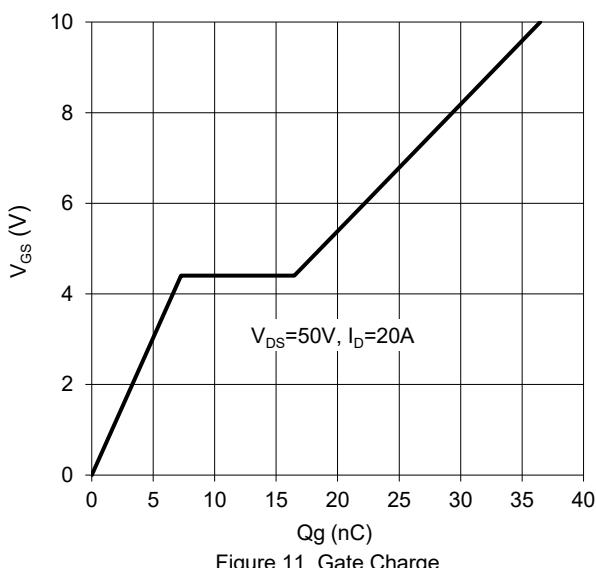


Figure 11. Gate Charge

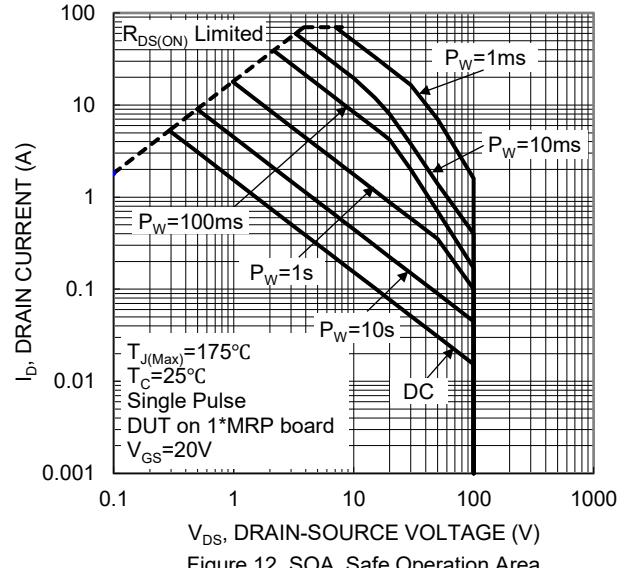


Figure 12. SOA, Safe Operation Area

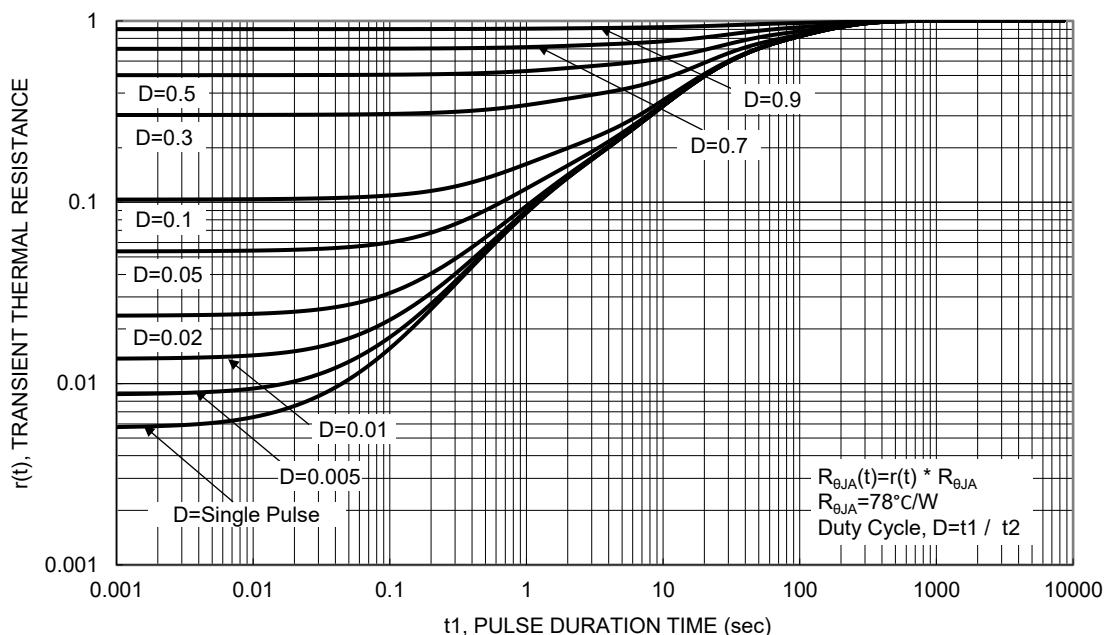
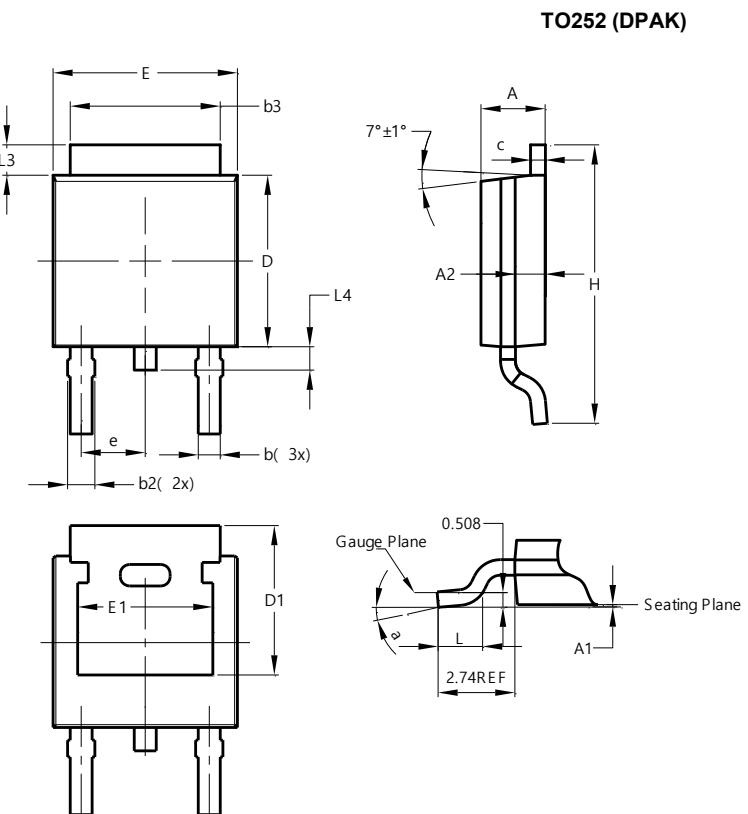


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

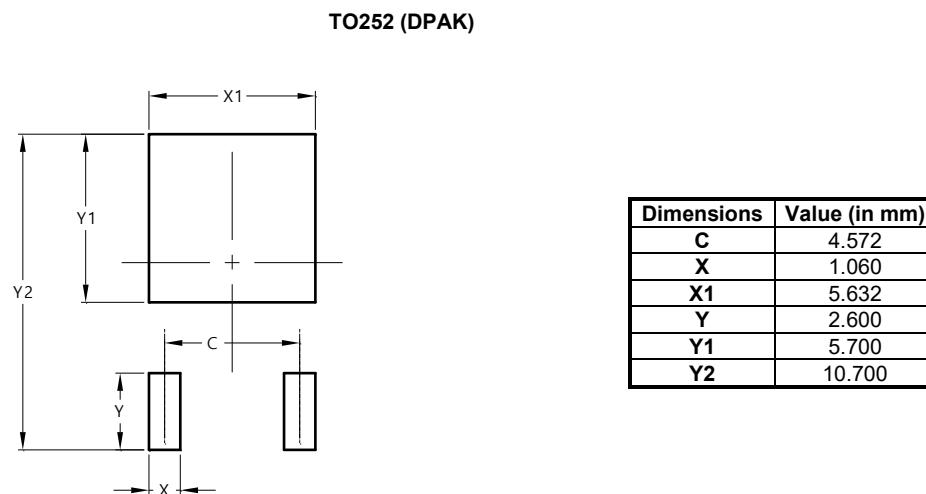


TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.50	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	--	--
e	2.286 BSC		
E	6.45	6.70	6.58
E1	4.32	--	--
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	--

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



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